07-85-0

PATENT

Docket No. JCLA7208 :

Date: 2- }-



ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Page 1

Transmitted herewith for filing is the patent application of

Inventor(s): CHIA-PIN LIN

CHIH-PENG FAN

CHANG-YUN HUNG

SHENG-CHOU LEE

METHOD OF LAMINATING COPPER FOIL ONTO A PRINTED CIRCUIT BOARD

Enclosed are:

- (X) Specification in (11) pages.
- (3) sheets of drawings.
- Return prepaid postcard.

Note:

THIS APPLICATION IS FILED UNSIGNED AND UNPAID

Jiawei Huang

Registration No. 43,330

Please send communications to:

J.C. Patents 1340 Reynolds Ave., #114

Irvine, CA 92614 Tel.: (949) 660-0761 Fax: (949)-660-0809



1340 REYNOLDS AVE., SUITE 114 IRVINE, CALIFORNIA 92614

(949) 660-0761

FAX: (949) 660-0809

Assistant Commissioner for Patents Washington, D.C. 20231

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

: JCLA7208

Applicant(s)

: Chia-Pin Lin, Chih-Peng Fan, Chang-Yun Hung,

Sheng-Chou Lee

For

: METHOD OF LAMINATING COPPER FOIL

ONTO A PRINTED CIRCUIT BOARD

"Express Mail"

: EL 800897372 US

Mailing Label No.

Date of Deposit

: July 3, 2001

I hereby certify that the accompanying

Transmittal in Duplicate; Specification 11 pages, 3 sheets of drawings; SIGNED Declaration and Power of Attorney 0 pages; Recordation Form Cover Sheet and Assignment 0 pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Michelle Chang